V_{DSS} 40 V
I_D 50 A
$R_{DS(ON)}$ 6.1 mΩ

Features

Uses advanced SGT technology
Extremely low $R_{DS(on)_typ}$=6.1mΩ@V_{gs}=10V
Excellent gate charge x RDS(on) product(FOM)

Application

Motor Drives
SR (Synchronous rectification)
DC/DC converter
General purpose applications

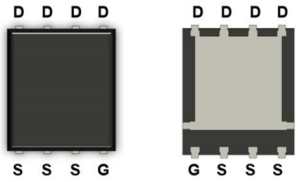
GK xxx
S006N04

LOGO GK xxx CODE

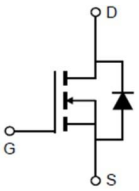
S006N04

RDS(ON) VDSS

PDFN5X6-8L top&bottom view



Equivalent Circuit



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings (T_C=25℃ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	40	V
Continuous drain current T_C = 25°C T_C = 100°C	I_D	50 35	A
Pulsed drain current T_C = 25°C, t_p limited by T_{jmax}	$I_{D\ pulse}$	200	
Avalanche energy, single pulse (L=0.5mH,Rg=25Ω)	E_{AS}	64	mJ
Gate-Source voltage	V_{GS}	±20	V
Power dissipation T_C = 25°C	P_D	31	W
Operating junction and storage temperature	T_j , T_{stg}	-55~150	℃

Thermal Resistance

Parameter	Symbol	Value	Unit
Thermal resistance, junction – case. Max	R_{thJC}	4.03	℃/W
Thermal resistance, junction – ambient. Max	R_{thJA}	58	

Electrical Characteristics (T_J=25℃unless otherwise noted)

Parameter	Symbol	Test Condition	Value			Unit
			min.	typ.	max.	
Static Characteristic						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS}=0V, I_D=250uA	40	-	-	V
Gate threshold voltage	$V_{GS(th)}$	V_{DS}=V_{GS},I_D=250uA T_j=25°C	1.2	1.6	2.2	V
Zero gate voltage drain current	I_{DSS}	V_{DS}=40V,V_{GS}=0V T_j=25°C	-		1	μA
Gate-source leakage current	I_{GSS}	V_{GS}=20V,V_{DS}=0V	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS}=10V, I_D=25A, T_j=25°C	-	6.1	7.5	mΩ
		V_{GS}=4.5V, I_D=25A, T_j=25°C	-	8.5	10.1	
Transconductance	g_{fs}	V_{DS}=5V,I_D=25A	-	84	-	S
Dynamic Characteristic						
Input Capacitance	C_{iss}	V_{GS}=0V, V_{DS}=20V, f=1MHz	-	2133	-	pF
Output Capacitance	C_{oss}		-	699	-	
Reverse Transfer Capacitance	C_{rss}		-	23	-	
Gate Total Charge	Q_G	V_{GS}=10V, V_{DS}=20V, I_D=50A	-	17	-	nC
Gate-Source charge	Q_{gs}		-	7	-	
Gate-Drain charge	Q_{gd}		-	2	-	
Turn-on delay time	$t_{d(on)}$	T_j=25°C, V_{GS}=10V, V_{DS}=40V, R_L=3.5Ω	-	8	-	ns
Rise time	t_r		-	24	-	
Turn-off delay time	$t_{d(off)}$		-	13	-	
Fall time	t_f		-	6	-	
Gate resistance	R_G	V_{GS}=0V, V_{DS}=0V, f=1MHz	-	4	-	Ω
Body Diode Characteristic						
Body Diode Forward Voltage	V_{SD}	V_{GS}=0V,I_{SD}=25A	-	-	1.2	V
Body Diode Reverse Recovery Time	t_{rr}	I_F=25A, dI/dt=500A/μs	-	18	-	ns
Body Diode Reverse Recovery Charge	Q_{rr}	I_F=25A, dI/dt=500A/μs	-	5	-	nC

RATING AND CHARACTERISTIC CURVES

Fig 1: Output Characteristics

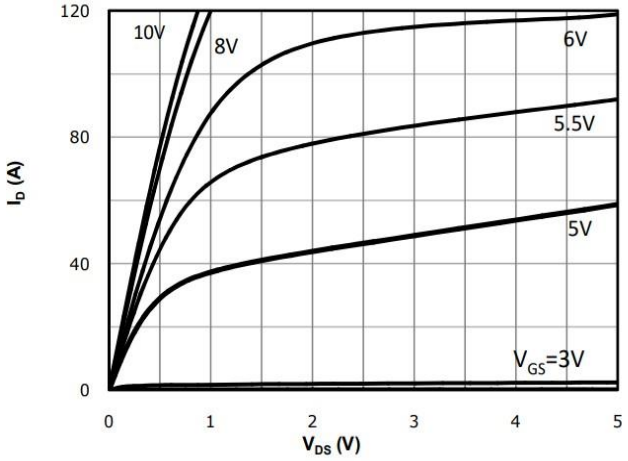


Fig 2: Transfer Characteristics

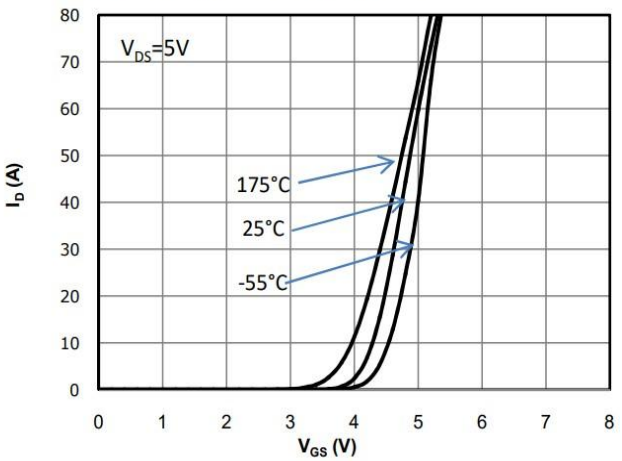


Fig 3: Rds(on) vs Drain Current and Gate Voltage

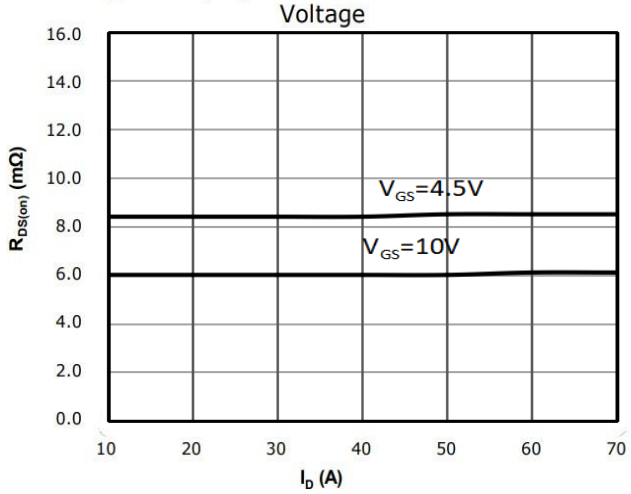


Fig 4: Rds(on) vs Gate Voltage

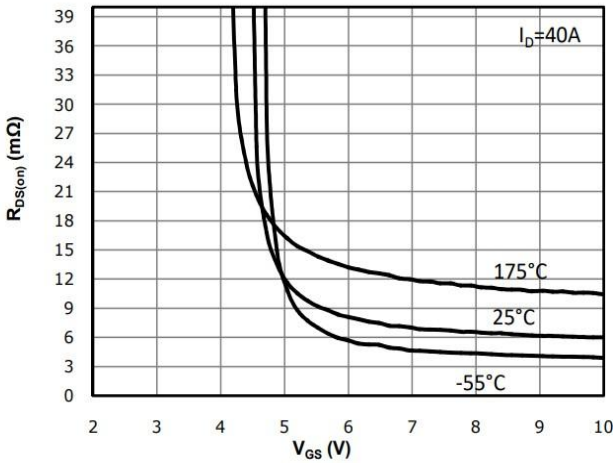


Fig 5: Rds(on) vs. Temperature

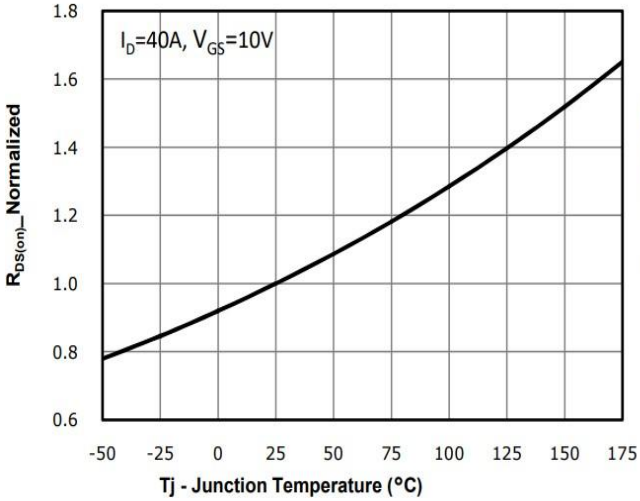
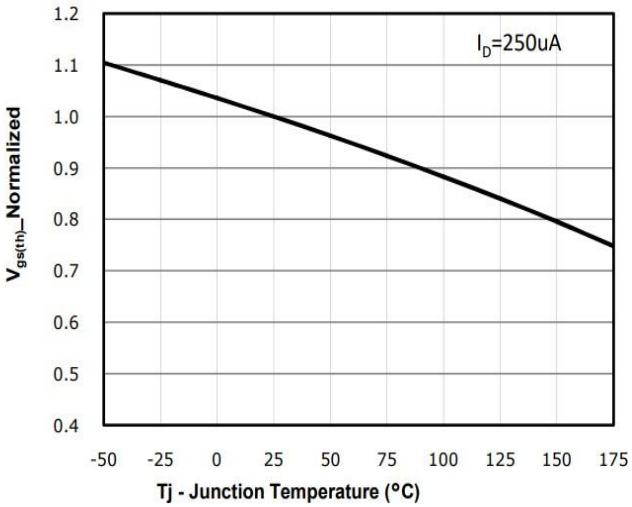


Fig 6: Vgs(th) vs. Temperature



RATING AND CHARACTERISTIC CURVES

Fig 7: BVdss vs. Temperature

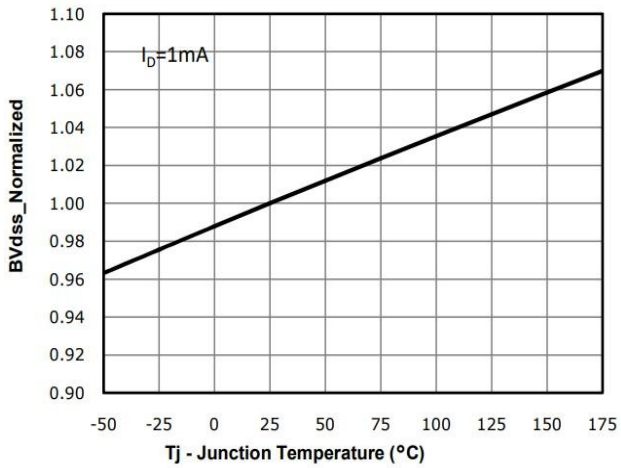


Fig 8: Capacitance Characteristics

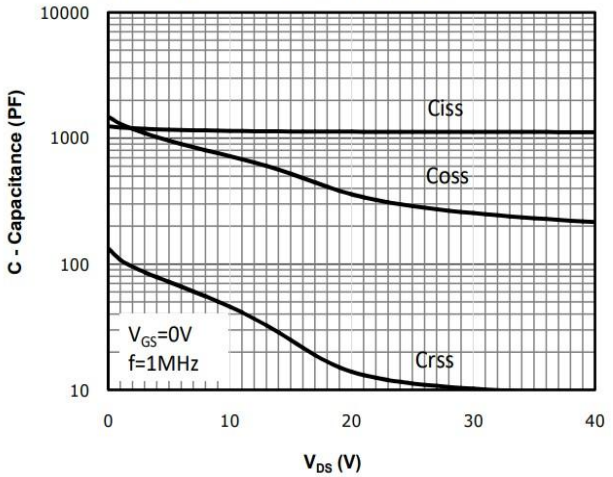


Fig 9: Gate Charge Characteristics

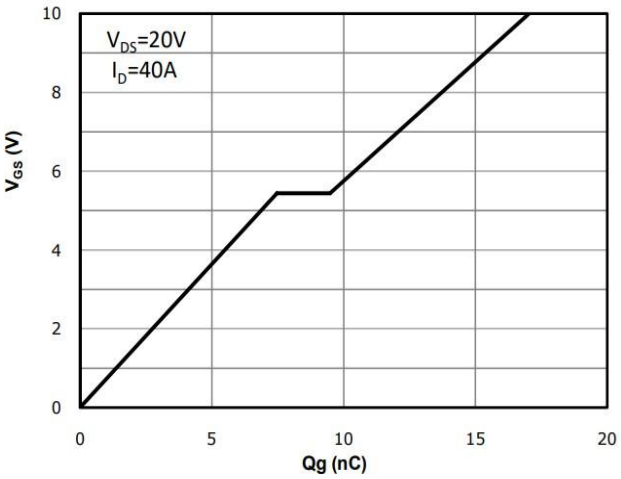


Fig 10: Body-diode Forward Characteristics

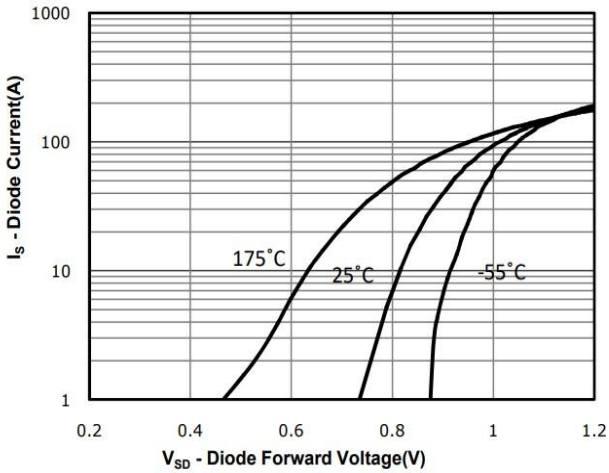


Fig 11: Power Dissipation

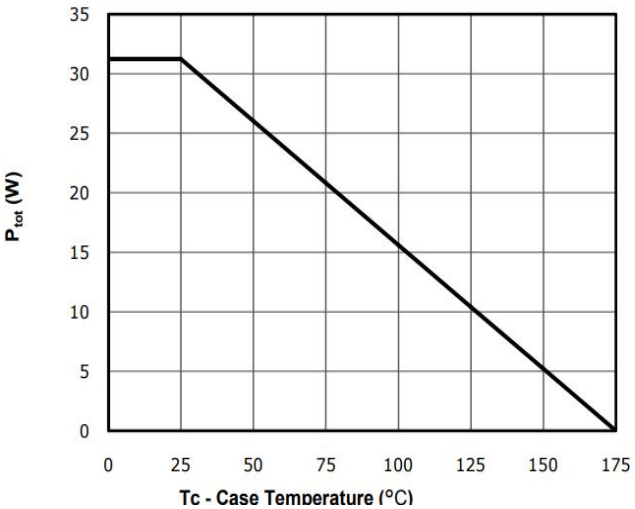
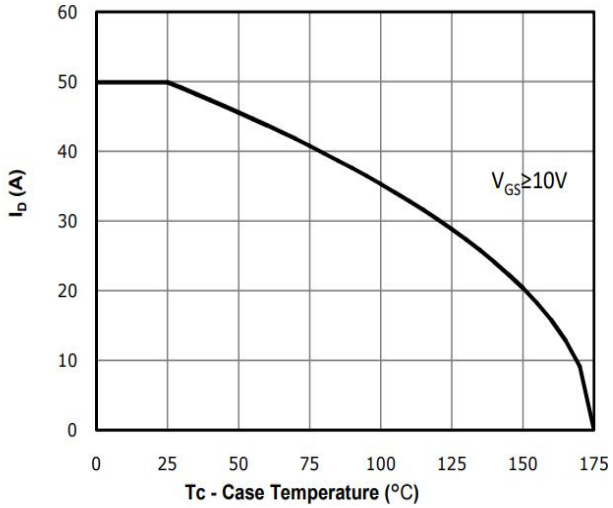


Fig 12: Drain Current Derating



RATING AND CHARACTERISTIC CURVES

Fig 13: Safe Operating Area

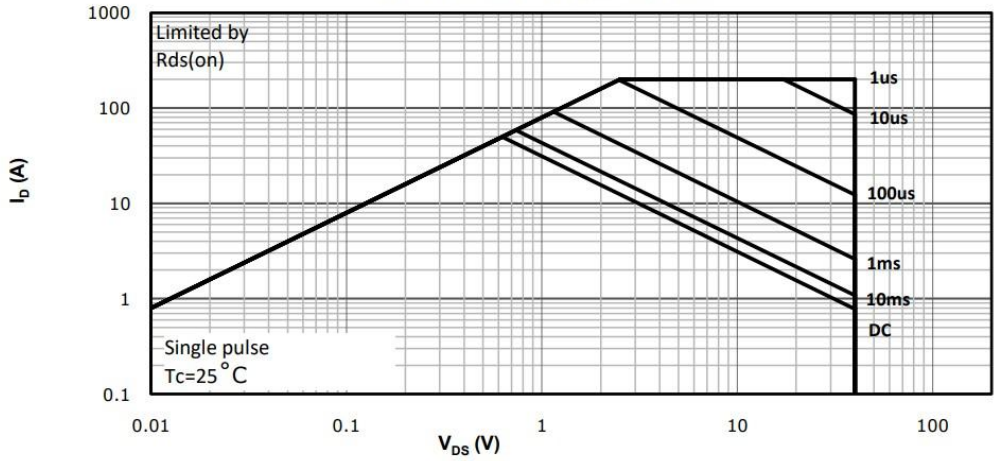
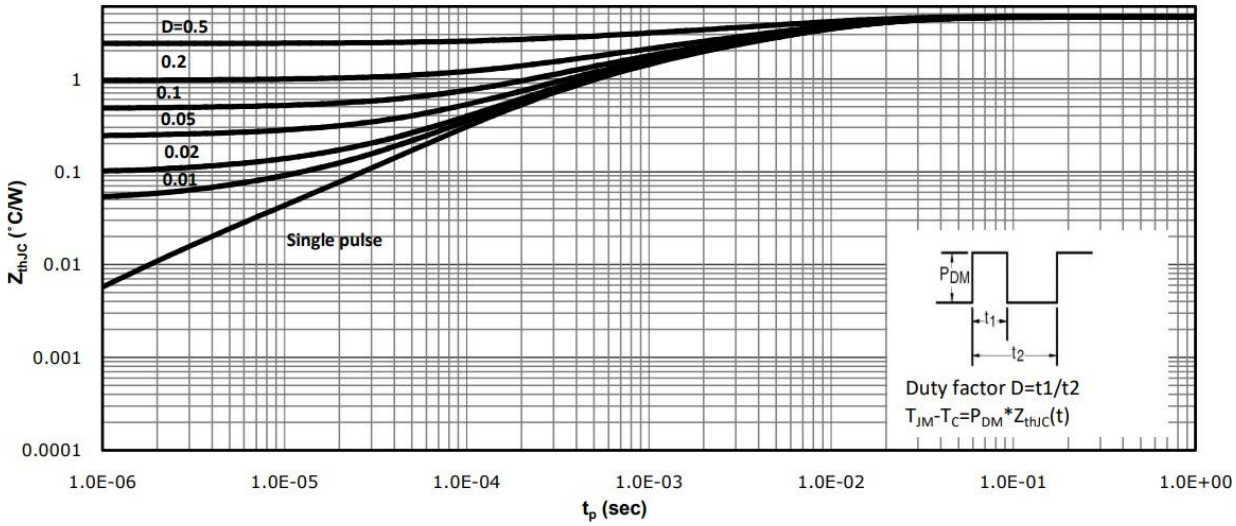
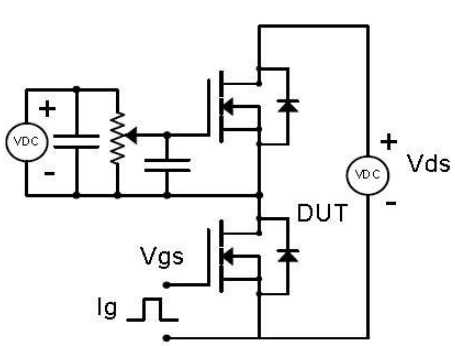


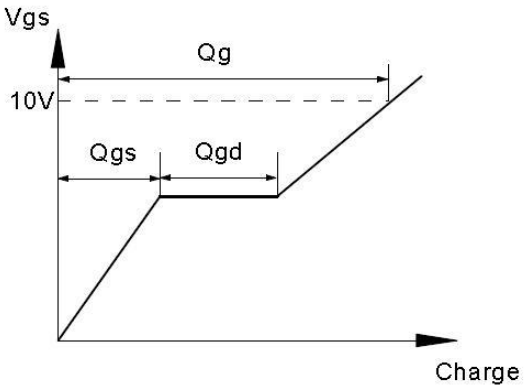
Fig 14: Max. Transient Thermal Impedance



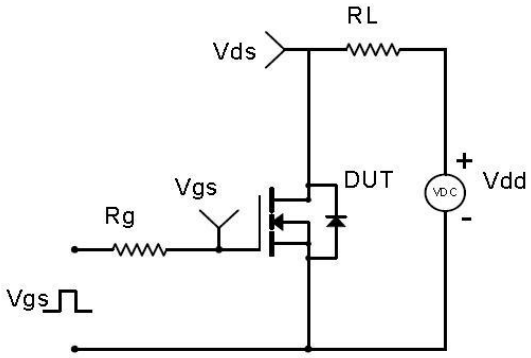
Test Circuit & Waveform

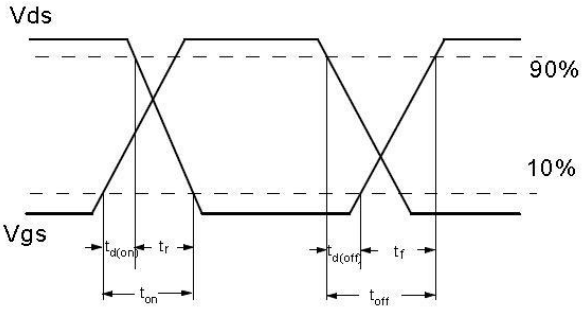
Gate Charge Test Circuit & Waveform



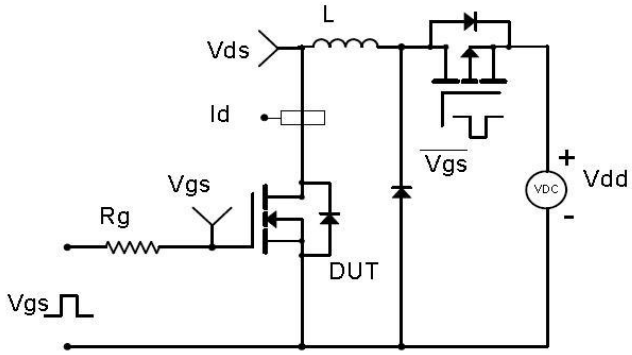


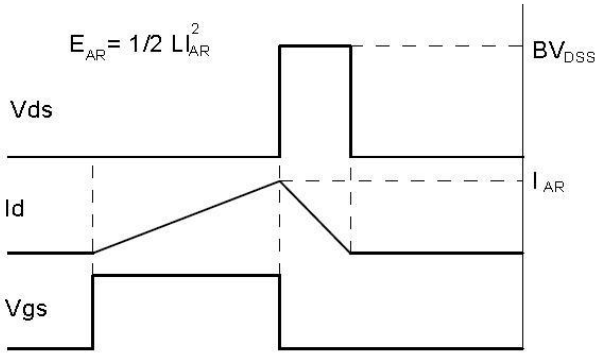
Resistive Switching Test Circuit & Waveforms



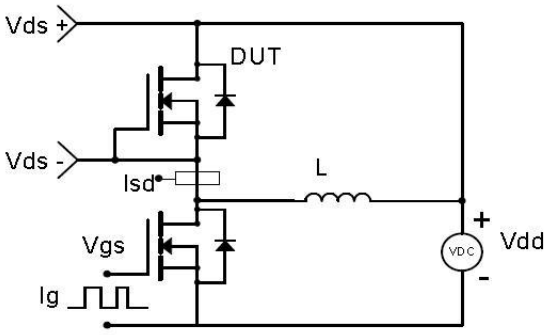


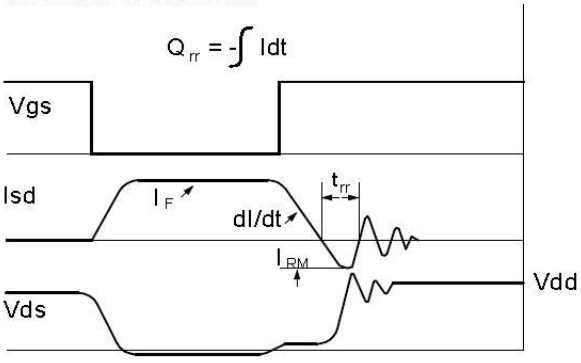
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms





Diode Recovery Test Circuit & Waveforms

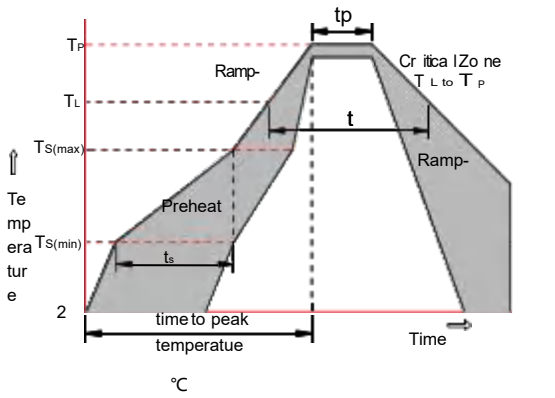




Soldering parameters

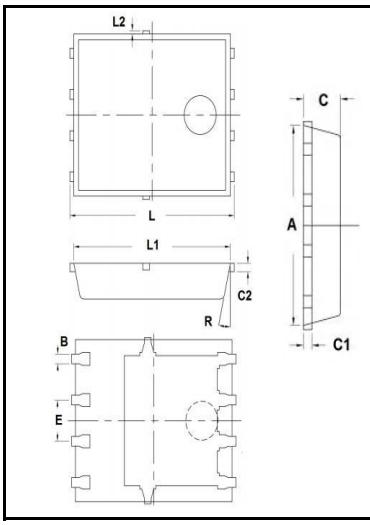
Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃ of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃

FIG5: Reflow condition



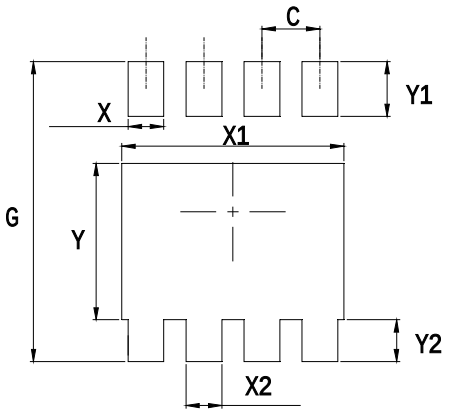
Package Dimensions & Suggested Pad Layout

PDFN5*6



Dim.	Min.	Max.
A	4.8	5.2
B	0.25	0.35
C	1	1.2
C1	Typ0.254	
C2	Typ0.254	
E	Typ1.27	
L	6	6.3
L1	5.7	6
L2	Max0.2	
R	Typ13°	

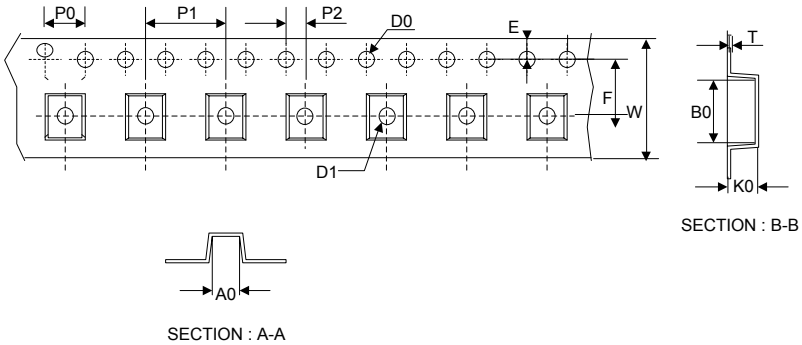
All Dimensions in millimeter



Dimensions	Value (in mm)
C	1.27
G	6.45
X	0.62
X1	4.50
X2	0.62
Y	3.70
Y1	1.05
Y2	0.80

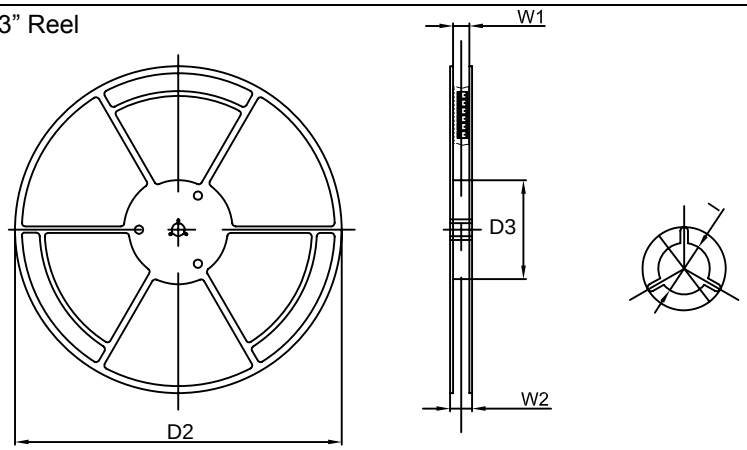
Tape & rell specification

Tape



Symbol	Dimension (mm)
P0	4.00±0.20
P1	8.00±0.20
P2	2.00±0.20
D0	1.55±0.20
D1	1.55±0.20
E	1.75±0.20
F	5.50±0.20
W	12.00±0.20
A0	6.60±0.20
B0	5.70±0.20
K0	1.30±0.20
T	0.20±0.20

13” Reel



D2	330.0±5.0
D3	100.0±4.0
W1	12.0±5.0
W2	14.0±5.0
I	13.0±2.0

Quantity: 5000PCS